

N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☒ Surface-mounted package
- ☒ Super Trench
- ☒ Advanced trench cell design
- ☒ MSL1

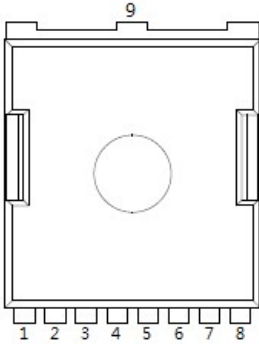
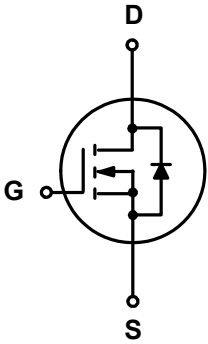
1.2 Applications

- ☒ BMS
- ☒ Drones
- ☒ High power inverter system
- ☒ Light electric vehicles

1.3 Quick reference

- ☒ $BV \geq 100 \text{ V}$
- ☒ $P_{tot} \leq 238 \text{ W}$
- ☒ $I_D \leq 300 \text{ A}$
- ☒ $R_{DS(ON)} \leq 1.1 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$
- ☒ $R_{DS(ON)} \leq 1.5 \text{ m}\Omega @ V_{GS} = 6 \text{ V}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)	 Top View TOLL	
2,3,4,5,6,7,8	Source(S)		
9	Drain(D)		

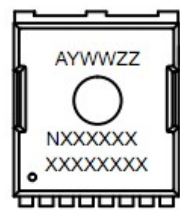
3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_C = 25\text{ }^{\circ}\text{C}$	100	-	V
V_{GS}	Gate-Source Voltage	$T_C = 25\text{ }^{\circ}\text{C}$	-	± 20	V
I_D^*	Drain Current (DC)	$T_C = 25\text{ }^{\circ}\text{C}, V_{GS} = 10\text{ V}$	-	300	A
		$T_C = 100\text{ }^{\circ}\text{C}, V_{GS} = 10\text{ V}$	-	211	A
$I_{DM}^{*,**}$	Drain Current (Pulsed)	$T_C = 25\text{ }^{\circ}\text{C}, V_{GS} = 10\text{ V}$	-	1200	A
P_{tot}	Drain power dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	-	238	W
T_{stg}	Storage Temperature		-55	175	$^{\circ}\text{C}$
T_J	Junction Temperature		-	175	$^{\circ}\text{C}$
I_S	Continuous-Source Current	$T_C = 25\text{ }^{\circ}\text{C}$	-	300	A
E_{AS}	Single Pulsed Avalanche Energy	$V_{DD}=50\text{ V}, L=1.0\text{ mH}$	-	3120	mJ
$R_{\theta JA}^{**}$	Thermal Resistance- Junction to Ambient		-	56	$^{\circ}\text{C/W}$
$R_{\theta JC}^{**}$	Thermal Resistance- Junction to Case		-	0.63	

Notes :

- * Pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
- ** Surface Mounted on minimum footprint pad area.
- *** Limited by bonding wire

4. Marking Information

Product Name	Marking
UP0D9N10T	

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
UP0D9N10T	TOLL-8L			2000	

6. Electrical Characteristics ($T_A=25^\circ$ Unless Otherwise Noted)

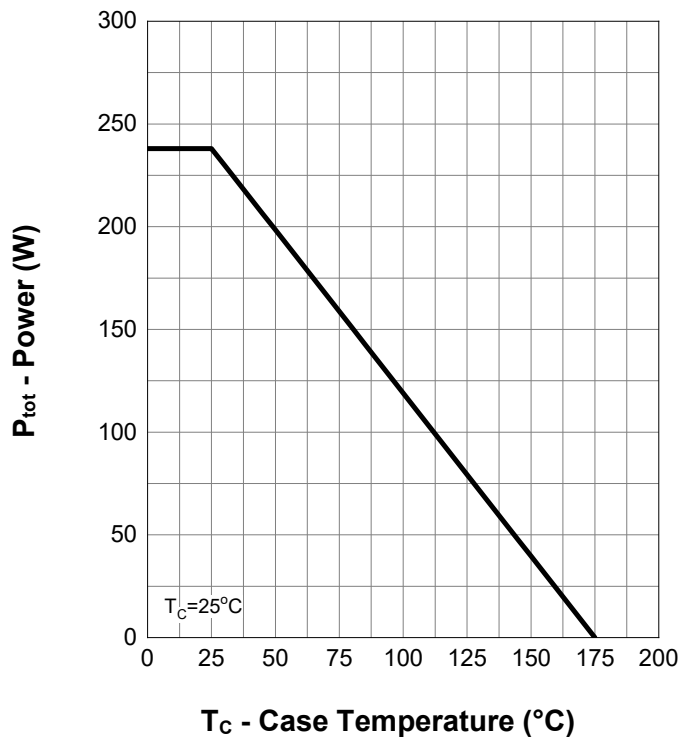
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _{DS} = 250 μA	100	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = -250 μA	2	-	4	V
I _{DSS}	Drain Leakage Current	V _{DS} = 80 V, V _{GS} = 0 V	-	-	1	μA
I _{GSS}	Gate Leakage Current	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	±100	nA
R _{DS(ON)} ^{Note1}	On-State Resistance	V _{GS} = 10 V, I _{DS} = 50 A	-	0.93	1.1	mΩ
		V _{GS} = 6 V, I _{DS} = 30 A	-	1.1	1.5	
Diode Characteristics						
V _{SD} ^{Note1}	Diode Forward Voltage	I _{SD} =50 A, V _{GS} = 0 V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _{DS} = 50 A, V _{GS} = 0 V dI _{SD} /dt = 100 A/μs	-	177	-	nS
Q _{rr}	Reverse Recovery Charge		-	263	-	nC
Dynamic Characteristics ^{Note2}						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = 50 V Frequency = 1 MHz	-	15282	-	pF
C _{oss}	Output Capacitance		-	2345	-	
C _{rss}	Reverse Transfer Capacitance		-	238	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = 50 V, V _{GEN} = 10 V, R _G = 3.9 Ω, R _L = 1 Ω, I _{DS} = 50 A	-	43	-	nS
t _r	Turn-on Rise Time		-	120	-	
t _{d(off)}	Turn-off Delay Time		-	166	-	
t _f	Turn-off Fall Time		-	117	-	
Gate Charge Characteristics ^{Note2}						
Q _g	Total Gate Charge	V _{DS} = 50 V, V _{GS} = 10 V, I _{DS} = 50 A	-	267	-	nC
Q _{gs}	Gate-Source Charge		-	83	-	
Q _{gd}	Gate-Drain Charge		-	66	-	

Note 1: Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

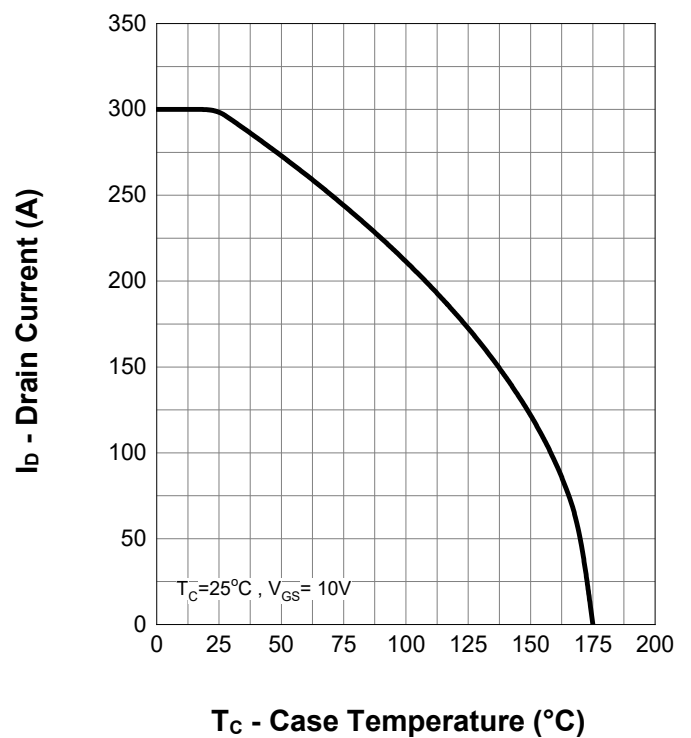
Note 2: Guaranteed by design, not subject to production testing.

7. Typical Characteristics

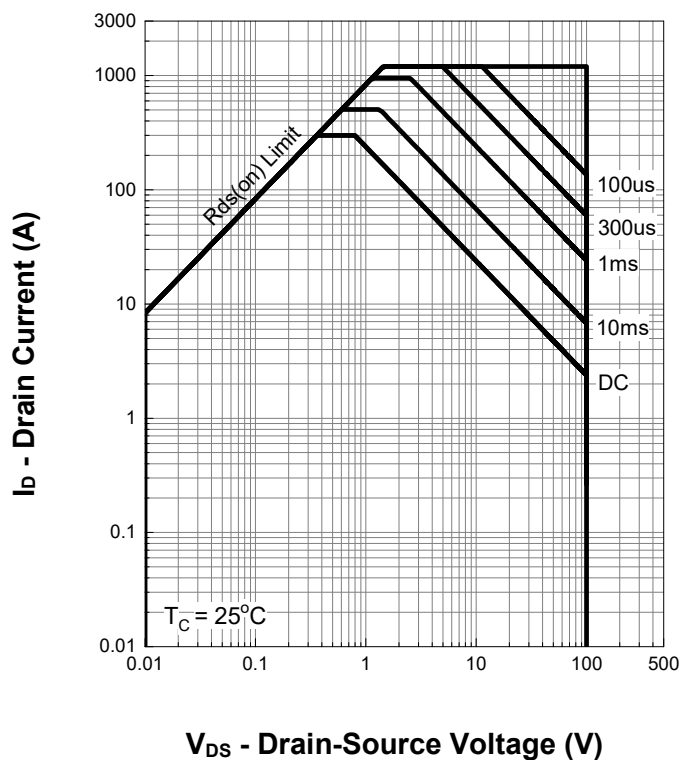
Power Capability



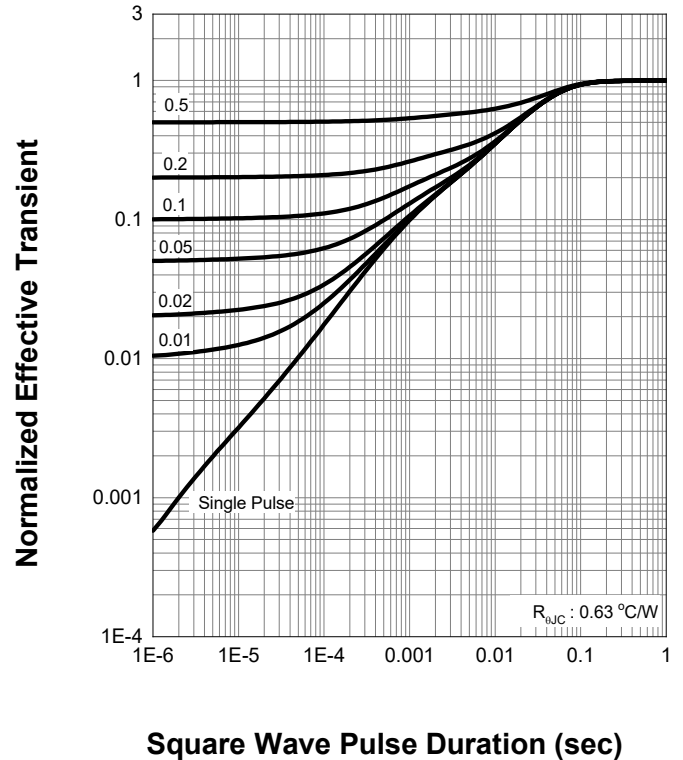
Current Capability



Safe Operating Area

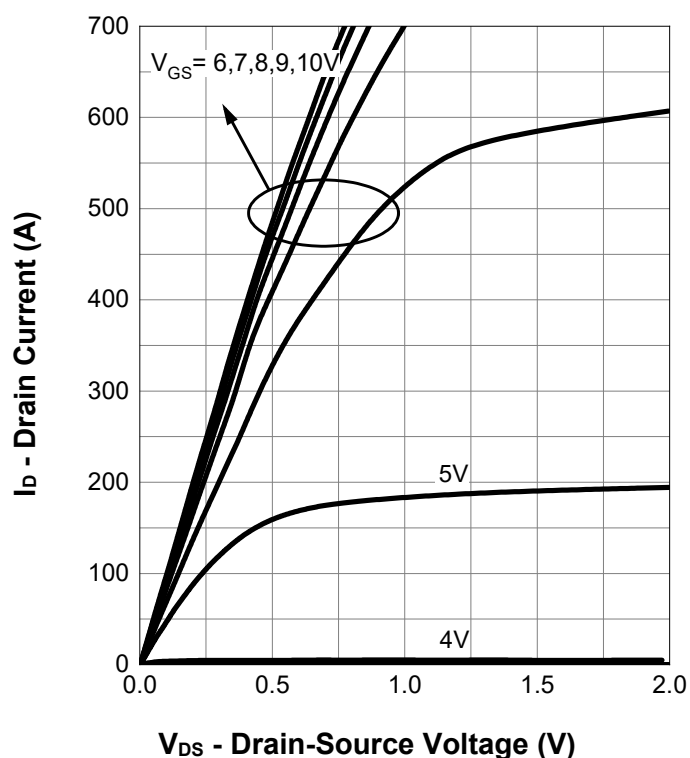


Transient Thermal Impedance

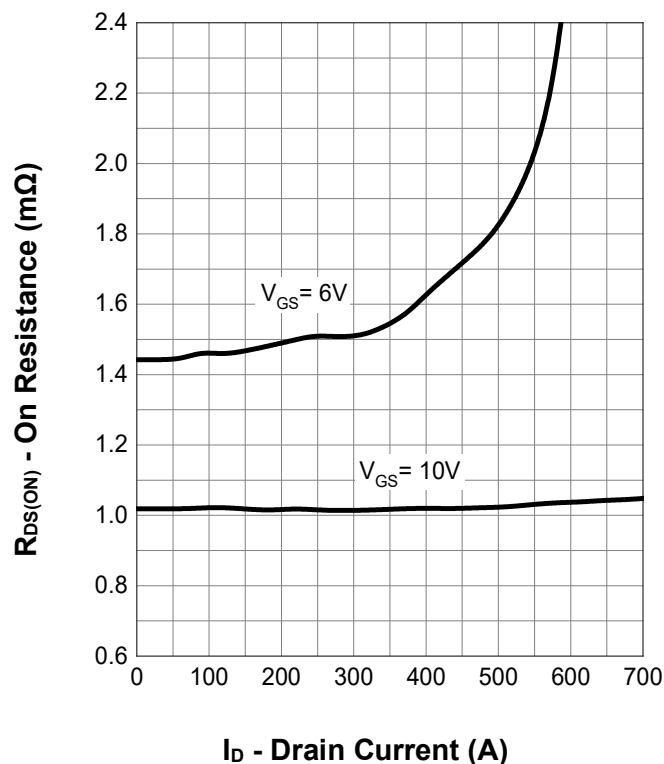


7. Typical Characteristics (cont.)

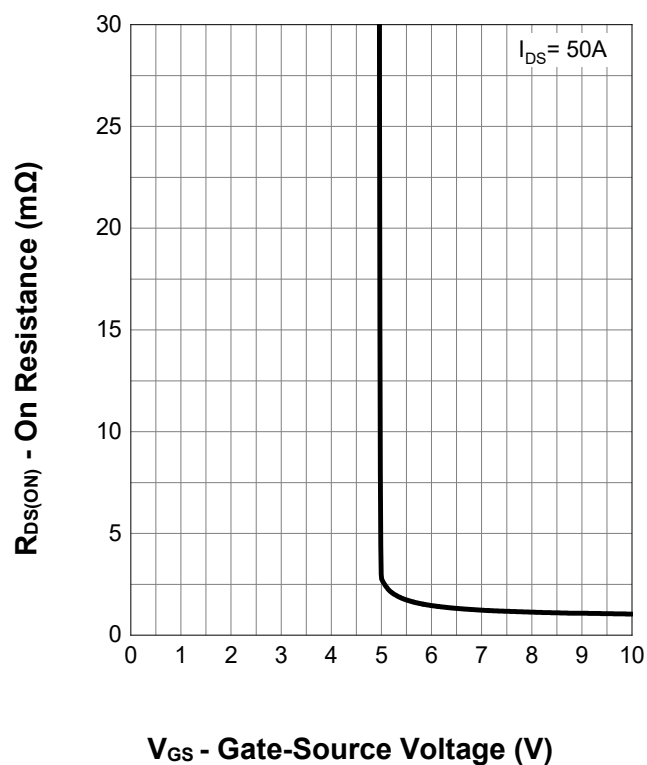
Output Characteristics



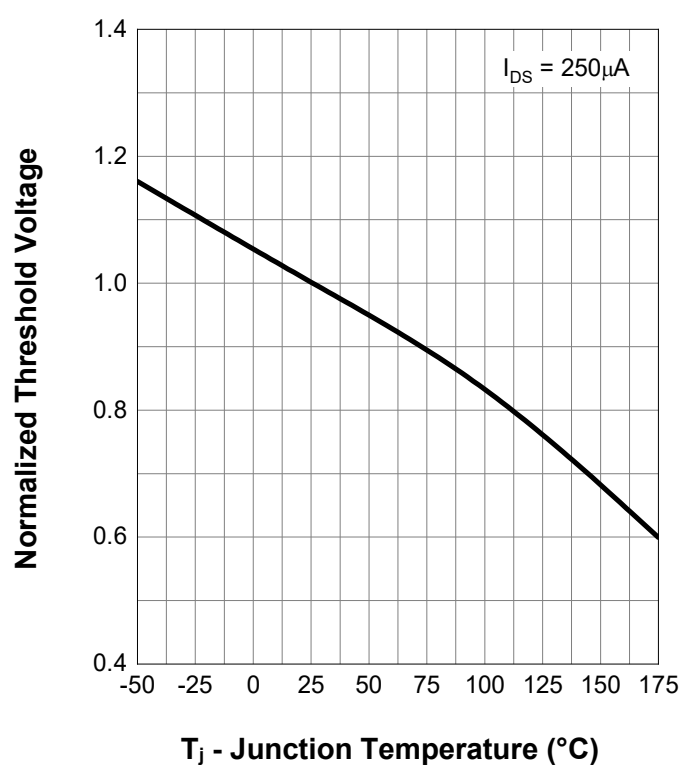
On Resistance



Transfer Characteristics

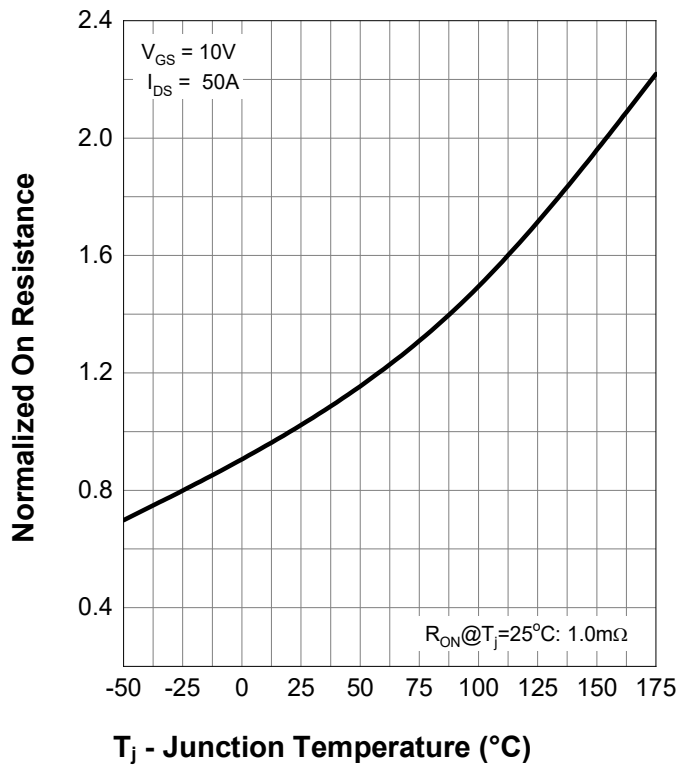


Normalized Threshold Voltage

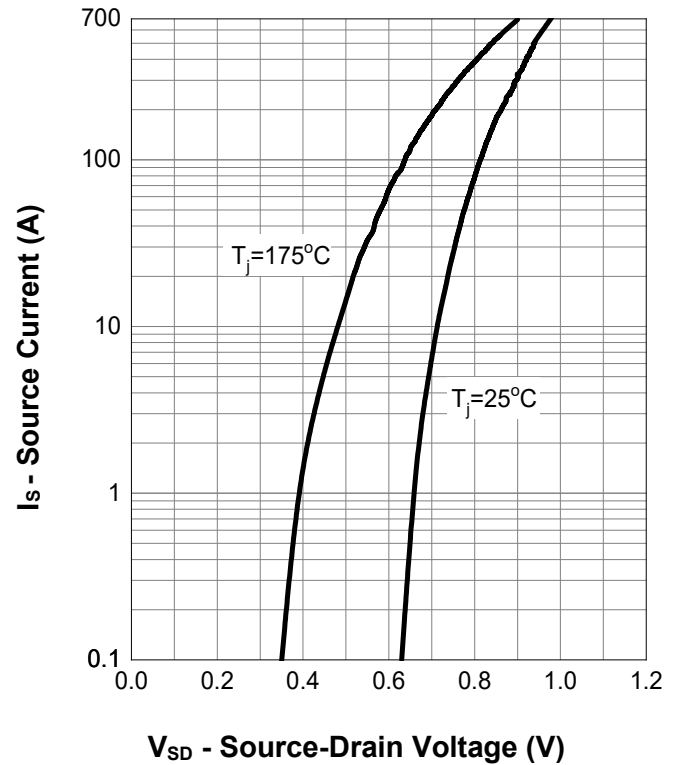


7. Typical Characteristics (cont.)

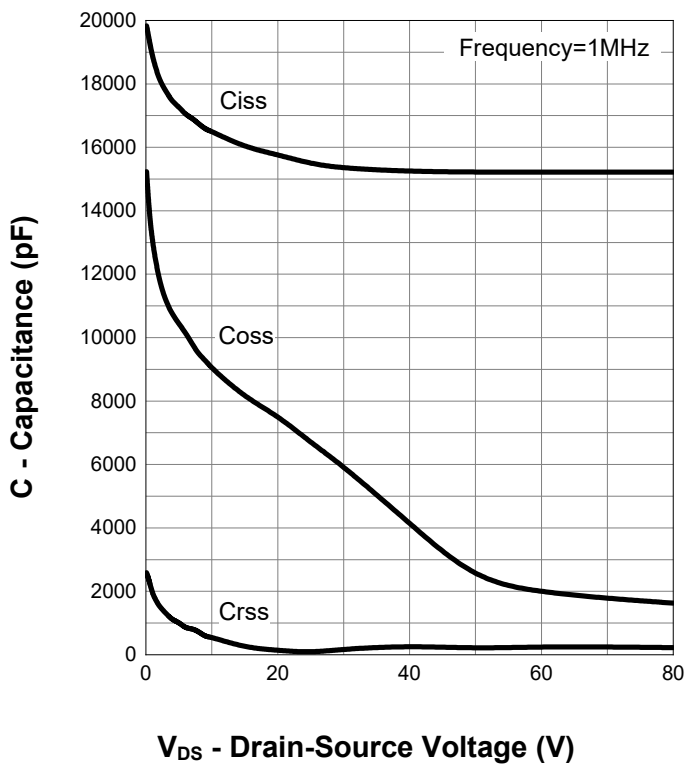
Normalized On Resistance



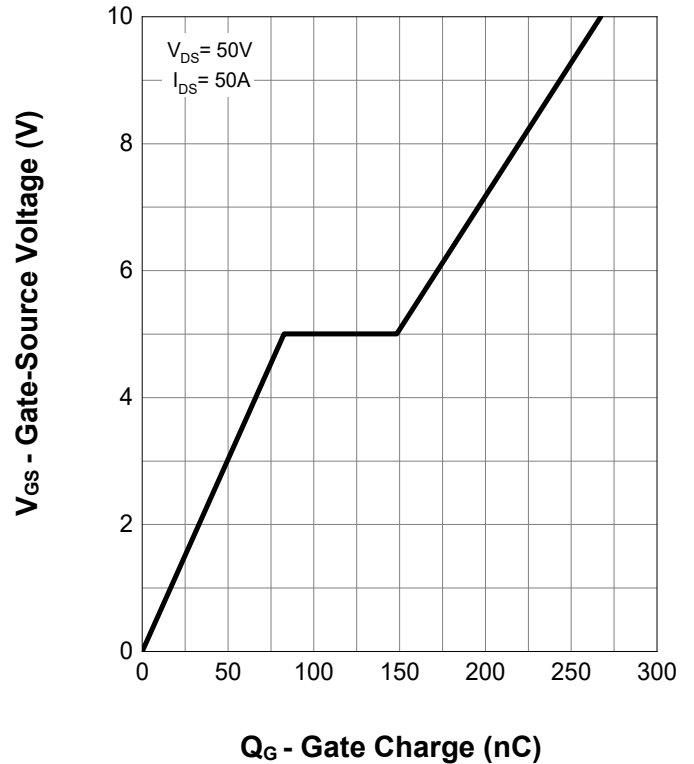
Diode Forward Current



Capacitance

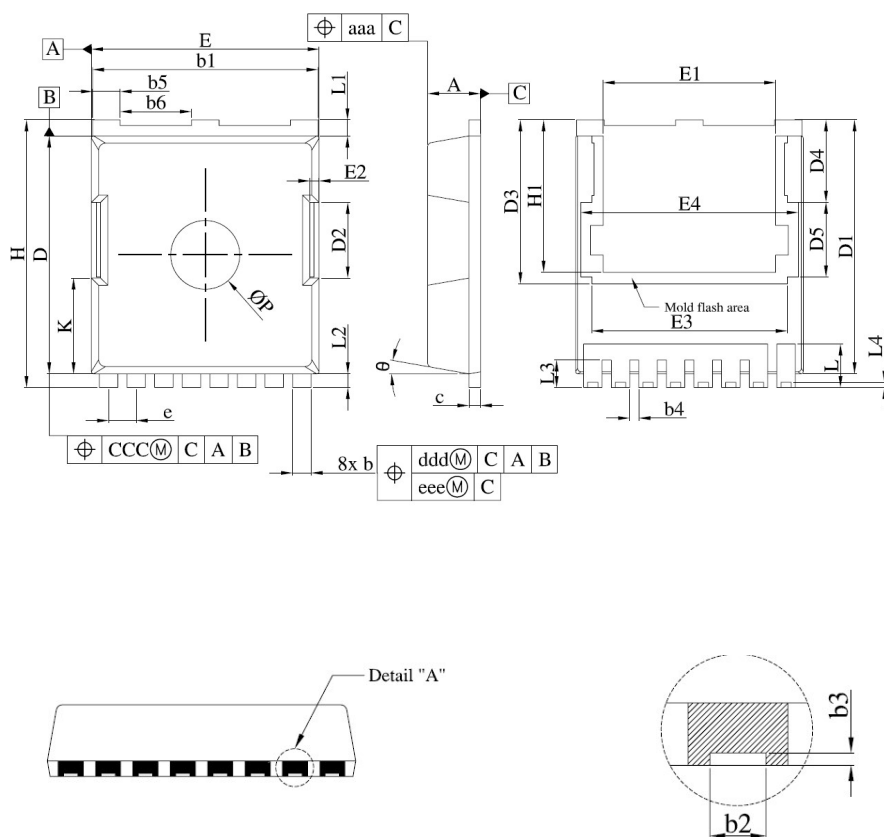


Gate Charge



8. Package Dimensions

TOLL-8L Package



Symbol	Dimensions In Millimeters		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.36	0.45	0.55
b3	0.05	0.10	/
b4	0.30	0.40	0.50
b5	1.10	1.20	1.30
b6	3.00	3.10	3.20
c	0.40	0.50	0.60
D	10.28	10.38	10.55
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D3	7.15		
D4	3.59		
D5	3.26		
e	1.10	1.20	1.30
E	9.80	9.90	10.00
E1	7.40	7.50	7.60
E2	0.30	0.40	0.50
E3	8.50		
E4	9.46		
H	11.50	11.68	11.85
H1	6.55	6.65	6.75
K	4.08	4.18	4.28
L	1.60	1.90	2.10
L1	0.50	0.70	0.90
L2	0.50	0.60	0.70
L3	1.00	1.20	1.30
L4	0.13	0.23	0.33
p	2.85	3.00	3.15
θ	10°REF		
aaa	0.20		
ccc	0.20		
ddd	0.25		
eee	0.20		